

Date: April 2021
Rev: V
No. of Components: One
Mix Ratio by Weight: N/A
Specific Gravity: 1.22
Pot Life: 28 Days
Shelf Life- Syringe: One year at -40°C

Recommended Cure: 130°C / 30 minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

Product Description: EPO-TEK® OD1361 (formerly R&D # 121-136-1) is an optically opaque epoxy. It is specially designed as the dam component for dam and fill applications in combination with either EPO-TEK® 121-136-3 or EPO-TEK® 121-136-4 fill formulations. It can be used for adhesive, sealing and encapsulation applications in semiconductor, electro-optics, fiber optics, circuit assembly, medical and scientific/OEM industries as well as for blocking out light in opto-packages.

Typical Properties: Cure condition: 130°C / 30 minutes. Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:

* Color (before cure):	Black
* Consistency:	Smooth Thixotropic Paste
* Viscosity (23°C) @ 10 rpm:	20,132 cPs
Thixotropic Index:	3.1
* Glass Transition Temp:	174 °C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):	
Below Tg:	58 x 10 ⁻⁶ in/in°C
Above Tg:	188 x 10 ⁻⁶ in/in°C
Shore D Hardness:	86
Die Shear @ 23°C:	39.1 Kg
Degradation Temp:	402 °C
Weight Loss:	
@ 200°C:	0.05 %
@ 250°C:	0.32 %
@ 300°C:	1.07 %
Suggested Operating Temperature:	< 350 °C (Intermittent)
Storage Modulus:	294,790 psi
Particle Size:	≤ 10 microns

Epoxyes and Adhesives for Demanding Applications™

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

EPOXY TECHNOLOGY, INC.

14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782

www.epotek.com